Abstract

Method for polishing a semiconductor wafer

A method for polishing a semiconductor wafer, comprising polishing of one side of the semiconductor wafer by means of a polishing pad which is fixed on a polishing plate and which contains fixedly bonded abrasive materials, while a polishing agent is introduced between that side of the semiconductor wafer which is to be polished and the polishing pad, wherein the semiconductor wafer is held during the polishing by means of a holding system, which is fixed on a carrier and which comprises a lined cutout of the size of the semiconductor wafer to be received, in the cutout by means of adhesion by the side that is not to be polished, and the carrier is guided such that the semiconductor wafer temporarily projects with a part of its surface beyond the surface of the polishing pad during the polishing.

Fig. 1